

THERMAL PADS | HSP-8

ACCESSORIES



Features

- Thermal Pad suitable for NOVA22 PM67 Panel Mount SSRs
- Easy to use thermal interface material
- Excellent alternative to thermal grease

GENERAL SPECIFICATIONS

Description	Parameters
Material	Chomerics T725
Color	Pink
Thickness [inch (mm)]	0.005 (0.127)
Adhesive	No
Thermal Impedance [°C-in ² /W] (1)	0.06 @ 25 psi
Thermal Conductivity [W/m-K] (1)	0.07
Flame Rating	V0
Continuous Temperature Range [°C]	-55 to 125
Volume Resistivity [Ohm-cm]	> 10 ⁴

MOUNTING SURFACE PREPARATION

The mounting surface, usually the heat sink, should be clean and free from machining oils and aluminum dust, and may be cleaned with any common solvent, such as isopropyl alcohol (IPA) if necessary. The surface of the heat sink may be anodized, chromate coated or unfinished aluminum.

INSTALLATION OF HSP-8 PADS

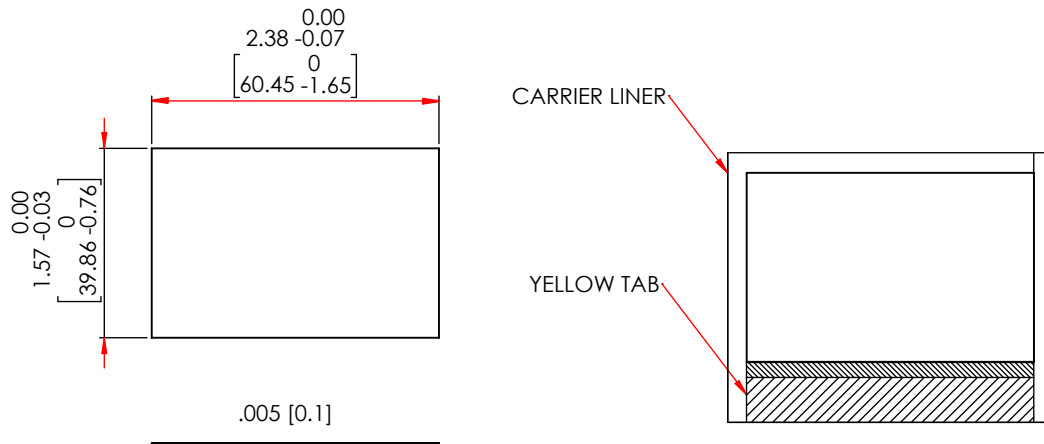
HSP-8 material does not require pre-heating of the heat sink prior to installing the HSP-8 pad onto the heat sink, because of the phase change nature of the HSP-8 material, please follow the process temperature/pressure guidelines below to ensure the best results for a specific assembly process:

Temperature / Pressure	
Process Step	Recommended Range
Removing pad from clear carrier liner	Temp. of Roll: less than 38°C (100°F)
Installing pad onto "cold" heat sink	Heat Sink Temp: 16°C to 38°C (60°F to 100°F)
	Roll Temp: 21°C to 38°C (70°F to 100°F)
	Installation Pressure: 25 to 50 psi (2)
Installing pad onto "warm" heat sink	Heat Sink Temp: 24°C to 38°C (75°F to 100°F)
	Roll Temp: 21°C to 38°C (70°F to 100°F)
	Installation Pressure: 25 to 50 psi (2)
Removing protective blue release liner	Temp of Heat Sink/Pad Assembly: Less than 38°C (100°F)

When removing the pull-tab, use a quick, lifting motion. This is preferable over peeling the pull-tab from the HSP-8 pad and heat sink. To ensure optimal "wetting" of the HSP-8 pad to the heat sink. It is recommended that the parts be allowed to dwell one hour prior to attempting release liner removal.

MECHANICAL SPECIFICATIONS

Tolerances: ±0.02 in / 0.5 mm
All dimensions are in: inches [Millimeters]



GENERAL NOTES

- (1) This value is provided for reference only. Follow installation instructions for accurate thermal performance.
- (2) Apply pressure to the HSP-8 pad with a soft "press-pad" for 2 to 3 seconds.

WARNINGS



RISK OF MATERIAL DAMAGE AND HOT ENCLOSURE

- The product's side panels may be hot, allow the product to cool before touching.
- Follow proper mounting instructions including torque values.
- Do not allow liquids or foreign objects to enter this product.

Failure to follow these instructions can result in serious injury, or equipment damage.



HAZARD OF ELECTRIC SHOCK, EXPLOSION OR ARC FLASH

- Disconnect all power before installing or working with this equipment.
- Verify all connections and replace all covers before turning on power.

Failure to follow these instructions will result in death or serious injury.

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